

Features

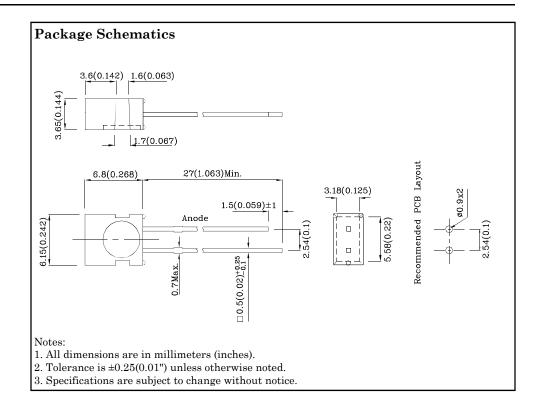
- Reliable & robust
- Low power consumption
- RoHS compliant







ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES



Absolute Maximum Ratings $(T_A=25^{\circ}C)$		Red (GaAlAs)	Unit		
Reverse Voltage	V_{R}	5	V		
Forward Current	I_{F}	30	mA		
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	155	mA		
Power Dissipation	P_{D}	75	mW		
Operating Temperature	T_{A}	-40 ~ +85			
Storage Temperature	Tstg	-40 ~ +85	°C		
Lead Solder Temperature [2mm Below Package Base]	260°C For 3 Seconds				
Lead Solder Temperature [5mm Below Package Base]	260°C For 5 Seconds				

A Relative Humidity between 40% and 60% is recommended in ESD-protected work areas to reduce static build up during assembly process (Reference JEDEC/JESD625-A and JEDEC/J-STD-033)

Operating Characteristics (T _A =25°C)		Red (GaAlAs)	Unit
Forward Voltage (Typ.) (I _F =20mA)	V_{F}	1.85	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) $(V_R=5V)$	I_R	10	uA
Wavelength of Peak Emission CIE127-2007* (Typ.) (I _F =20mA)	λP	655*	nm
Wavelength of Dominant Emission CIE127-2007* (Typ.) $(I_F=20\text{mA})$	λD	640*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	Δλ	20	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	45	pF

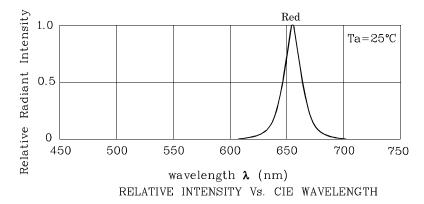
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity CIE127-2007* (I _F =20mA) mcd		Wavelength CIE127-2007* nm λΡ	Viewing Angle 20 1/2
				min.	typ.		
XEMR21D	Red	GaAlAs	Red Diffused	40 20*	98 49*	655*	140°

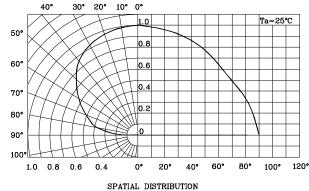
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

Aug 26,2016 XDSA1929 V8-X Layout: Maggie L.

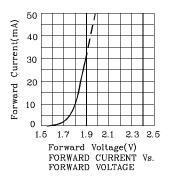


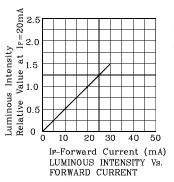


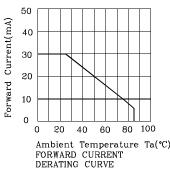


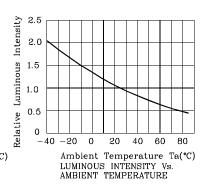


Red

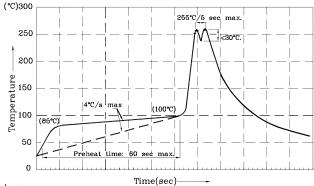








Wave Soldering Profile For Thru-Hole Products (Pb-Free Components)



Notes:

- Notes. I. Recommend pre-heat temperature of 105°C or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of $260^{\circ}C$ 2. Peak wave soldering temperature between $245^{\circ}C \sim 255^{\circ}C$ for 3 sec
- (5 sec max).
- 3.Do not apply stress to the epoxy resin while the temperature is above $85\,^\circ\text{C}.$ 4.Fixtures should not incur stress on the component when mounting and
- during soldering process. 5.SAC 305 solder alloy is recommended.
- 6. No more than one wave soldering pass

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

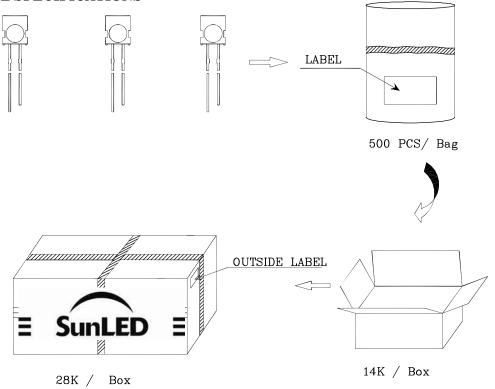
- 1. Wavelength: +/-1nm
- 2. Luminous Intensity / Luminous Flux: +/-15%
- 3. Forward Voltage: +/-0.1V

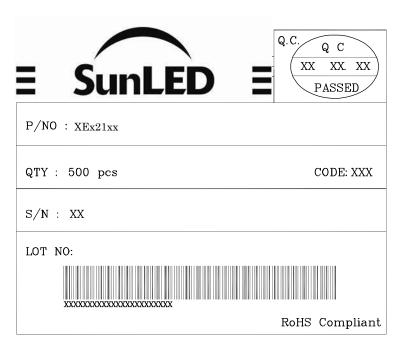
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





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Aug 26,2016